

<b>INFORMATION DISCLOSURE STATEMENT</b>  <i># 2</i>	Atty. Docket No.: 1065-US	Serial No.: Unassigned
	Applicant: Payer, et al.	Group: Unassigned <i>2539</i>
	Filing Date: Unassigned	Examiner: Unassigned

## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if appropriate
<i>TC</i>	AA	5,996,221	12/07/1999	Chirovsky, et al.	29	840	<i>25</i>
	AB						
	AC						
	AD						
	AE						
	AF						

## FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
<i>TC</i>	AG	98/53355	26 NOV 1998	WO	G02B	7/182		
	AH							
	AI							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

<i>TC</i>	AJ	Luk, C.F.; Chan, Y.C.; and Hung, K.C., "Development of Gold to Gold Interconnection Flip Chip Bonding for Chip on Suspension Assemblies," 2001 Electronic Components and Technology Conference.
	AK	
	AL	
	AM	
	AN	
	AO	

Examiner <i>T C Patel</i>	Date Considered <i>10/2/02</i>
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Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.